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(54) Title: SOLDER BALL PLACEMENT APPARATUS

(57) Abstract

An apparatus for placing an array of solder balls on a substrate (10) includes a carrier plate (18) having an array (80) of holes (82) therethrough. Each hole (82) is capable of holding a solder ball (102). A ball placement head (126) having an array of pins (108) is aligned with a desired pattern (81) of solder balls (102) held by the carrier plate (18). The array of pins (108) push the pattern of solder balls (102) through the holes (82) in the carrier plate (18) onto the substrate (10).

